

Electronic Patent Application Fee Transmittal

Application Number:	10613326			
Filing Date:	03-Jul-2003			
Title of Invention:	Vertical conduction flip-chip device with bump contacts on single surface			
First Named Inventor/Applicant Name:	Daniel M. Kinzer			
Filer:	Kourosh Salehi/Gloria Levy			
Attorney Docket Number:	IR-2541 DIV			

Filed as Large Entity

Utility under 35 USC 111(a) Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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Basic Filing:

Pages:

Claims:

Miscellaneous-Filing:

Petition:

Patent-Appeals-and-Interference:

Notice of appeal	1401	1	540	540
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Post-Allowance-and-Post-Issuance:

Extension-of-Time:

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				540